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INFORMATION DISCLOSURE STATEMENT BY APPLICANT <i>(use as many sheets as necessary)</i>		Application Number	Unknown
		Filing Date	(Herewith)
		First Named Inventor	Efren M. Lacap
		Art Unit	Unknown
		Examiner Name	Unknown
Sheet	1	of	2
		Attorney Docket Number	408204

U.S. PATENT DOCUMENTS

Examiner Initials *	Cite No. ¹	Document Number	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number - Kind Code ² (if known)			
80	1	US-5,553,769	09-10-1998	Ellerson et al.	
	2	US-4,604,644	08-05-1986	Beckham et al.	
	3	US-5,316,205	05-31-1994	Melton	
	4	US-5,918,792	07-06-1999	Stumpf et al.	
	5	US-6,278,264	08-21-2001	Burstein et al.	
	6	US-6,445,244	09-03-2002	Stratakos et al.	
	7	US-6,400,126	06-04-2002	Zuniga et al.	
	8	US-6,498,467	12-24-2002	Stratakos	
	9	US-6,445,169	09-03-2002	Schultz et al.	
	10	US-6,443,614	08-13-614	You et al.	
	11	US-6,462,522	10-08-2002	Burstein et al.	
	12	US-6,020,729	02-01-2000	Stratakos et al.	
	13	US-6,225,795	05-01-2001	Stratakos et al.	
	14	US-3,429,040	02-25-1989	Miller	
	15	US-3,401,128	09-10-1988	Miller et al.	
88	16	US-T955,008	02-01-1977	Gregor et al.	
		US-			

FOREIGN PATENT DOCUMENTS

Examiner Signature	<i>Joseph Q</i>	Date Considered	6/18/05
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OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No. ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
<i>JJ</i>	1	Figures 1, and 3-8 from "Oki Technical Review". http://www.oki.com/en/otr/html/nf/ , February 19, 2003, 5 pages	
	2	"Flip chip photographs of flip chip bumps, flip chip assemblies, flip chip interconnections", Flipchips dot com, http://www.flipchips.com/photos.html , February 13, 2003, 3 pages	
	3	"Flip-chip Packaging: a 32-Year-Old Infant Grows Up", Chip Scale Review Online, http://www.chipscalereview.com/issues/0701/fi_01.html , July, 2001, pp. 1-4	
	4	"Flip-chip Packaging: a 32-Year-Old Infant Grows Up", Chip Scale Review Online, http://www.chipscalereview.com/issues/0701/fi_02.html , July, 2001, pp. 1-5	
	5	"The Emerging Copper Revolution Will Impact ICs with Critical Dimensions 100nm", Chip Scale Review Online, http://www.chipscalereview.com/Issues/0301/techReport.html , March, 2001, pp. 1-3	
	6	"Making Microchips", http://www.glenco.com/norton/n-instructor-updates/2000/21100-7.html , February 19, 2003, pp. 1-4	
	7	"Process Defect Guides", ppm-monitoring.com, http://www.thepdfshop.com.uk/ppm/asp/wave.asp , July 2, 2003, 4 pages	
	8	"300mm Wafer Bumping", Technology Publishing - A division of Montgomery Research Europe Ltd., http://www.future-fab.com/documents.asp?grID=217&d_ID=1338 , July 1, 2003, 6 pages	
	9	XICOR, "CSP Packaging Technology ("B" Package Option)", Revised March, 2003, 11 pages, XICOR, Milpitas, CA	
	10	JASPER, JORG, "From Direct Chip Attach to Wafer Level CSP - A Modular Appropach to Serve Customer Needs", 5 pages, EM -Marin S.A. <i>no date avail.</i>	
	11	BICE, SHANNON B. and LI, YUZHOU, "Chemical Mechanical Polishing (CMP) for Computer Chip Manufacturing", 3 pages. <i>no date avail.</i>	
	12	ELENIUS, PETER, "The UltraCSP™ Wafer Scale Package", 8 pages, Flip Chip Technologies, Phoenix, AZ <i>no date avail.</i>	
	13	"STAYCHIP™ 3075F Underfill for Handheld Electronic Devices & System-in-Package", 15 pages, Cookson Electronics Semiconductor Products, Alpharetta, GA <i>no date avail.</i>	
	14	DURAH, DR. HAMIT, "Chip-on-Foil: An Emerging Technology for Display Driver Electronics", October 10, 2002, 33 pages, Phillips Semiconductors Zurich	
<i>JJ</i>	15	FJELSTAD, JOSEPH, "Wafer Level Packaging of Compliant CSPs Using Flexible Film Interposers", HDI Magazine, Spring 1999, 6 pages	
<i>JJ</i>	16	"Flip Chip Packaging for SRAM", Copyright 1999, 2 pages, IBM USA	
Examiner Signature	<i>Jonath JJ</i>		Date Considered 6/18/05

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